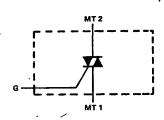
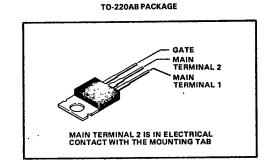
100000

device schematic

TIC226A, TIC226B, TIC226C, TIC226D, TIC216E, TIC226M, TIC226S, TIC226N **SILICON TRIACS** REVISED OCTOBER 1984

- **Sensitive-Gate Triacs**
- 100 V to 800 V
- 8 A RMS, 70 A Peak
- MAX IGT of 5 mA (Quadrant 1-3)





## absolute maximum ratings at 25°C case temperature (unless otherwise noted)

	TIC226A	TIC226B	TIC226C	TIC2260		
Repetitive peak off-state voltage, VDRM (see Note 1)	100 V	200 V	300 V	400 V		
Full-cyclè RMS on-state current at (or below) 85°C case temperature IT(RMS) (see Note 2)	8A					
Peak on-state surge current, full-sine-wave, ITSM(see Note 3)	70 A					
Peak on-state surge current half-sine-wave, ITSM (see Note 4)		80 A				
Peak gate current, IGM		1				
Peak gate power dissipation, P <sub>GM</sub> at (or below) 85°C case temperature (pulse duration ≤ 200 μs)	· 2.2 W					
Average gate power dissipation, PG(av), at (or below) 85°C case temperature (see Note 5)	0.9 W					
Operating case temperature range	- 40°C to 110°C					
Storage temperature range	- 40°C to 125°C					
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	230°C					

**TIC Devices** 

- NOTES: 1. These values apply bidirectionally for any value of resistance between the gate and Main Terminal 1.
  - 2. This value applies for 50-Hz full-sine-wave operation with resistive load. Above 85°C derate linearly to 110°C case temperature at the rate of 120 mA/°C.
  - 3. This value applies for one 50-Hz full-sine-wave when the device is operating at (or below) the rated value of on-state current. Surge may be repeated after the device has returned to original thermal equilibrium. During the surge, gate control may be lost.

    4. This value applies for one 50-Hz half-sine-wave when the device is operating at (or below) the rated value of on-state current.
  - Surge may be repeated after the device has returned to original thermal equilibrium. During the surge gate control may be lost.
  - 5. This value applies for a maximum averaging time of 20 ms.



62C 36725

D

TIC226A, TIC226B, TIC226C, TIC226D, TIC226E, TIC226M, TIC226S, TIC226N **SILICON TRIACS** 

T-25-15

## absolute maximum ratings at 25°C case temperature (unless otherwise noted)

	TIC226E	TIC226M	TIC226S	TIC226N	
Repetitive peak off-state voltage, VDRM (see Note 1)	500 V	600 V	700 V	800 V	
Full-cycle RMS on-state current at (or below) 85 °C case temperature 1T(RMS) (see Note 2)	8A				
Peak on-state surge current, full-sine-wave, ITSM(see Note 3)	70 A				
Peak on-state surge current half-sine-wave, ITSM (see Note 4)	80 A				
Peak gate current, IGM	1				
Peak gate power dissipation, P <sub>GM</sub> at (or below) 85°C case temperature (pulse duration ≤ 200 μs)	2.2 W				
Average gate power dissipation, PG(av), at (or below) 85°C case temperature (see Note 5)	0.9 W				
Operating case temperature range	- 40°C to 110°C				
Storage temperature range	- 40°C to 125°C				
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	230°C				

- NOTES: 1. These values apply bidirectionally for any value of resistance between the gate and Main Terminal 1.
  2. This value applies for 50-Hz full-sine-wave operation with resistive load. Above 85°C derate linearly to 110°C case temperature at the rate of 120 mA/°C.
  - 3. This value applies for one 50-Hz full-sine-wave when the device is operating at (or below) the rated value of on-state current.
  - Surge may be repeated after the device has returned to original thermal equilibrium. During the surge, gate control may be lost.

    4. This value applies for one 50-Hz half-sine-wave when the device is operating at (or below) the rated value of on-state current. Surge may be repeated after the device has returned to original thermal equilibrium. During the surge gate control may be lost.
  - This value applies for a maximum averaging time of 20 ms.



TIC Devices



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TIC226A, TIC226B, TIC226C, TIC226D, TIC226E, TIC226M, TIC226S, TIC226N **SILICON TRIACS** 

	PARAMETER	TEST	CONDITIONS		MIN TYP	MAX	UNI
DRM	Repetitive Peak Off-State Current	V <sub>DRM</sub> = Rated V <sub>DRM</sub> ,	1 <sub>G</sub> = 0,	T <sub>C</sub> = 110°C		± 2	m/
	Peak Gate Trigger Current	$V_{\text{supply}} = +12V^{\dagger}$ ,	R <sub>L</sub> = 10 Ω,	t <sub>W</sub> (g) ≥ 20 μs	2	50	
		$V_{\text{supply}} = +12V^{\dagger}$ ,	R <sub>L</sub> = 10Ω,	t <sub>W</sub> (g) ≥ 20 μs	- 12	- 50	m/
GTM		$V_{\text{supply}} = -12V^{\dagger}$ ,	R <sub>L</sub> = 10Ω,	t <sub>W{g}</sub> ≥ 20 μs	-9	- 50	,,,,
		$V_{\text{supply}} = -12V^{\dagger}$ ,	$R_L = 10 \Omega$ ,	t <sub>W</sub> (g) ≥ 20 μs	20		
	Peak Gate Trigger Voltage	$V_{\text{supply}} = +12V^{\dagger}$ ,	R <sub>L</sub> = 10 Ω,	t <sub>w(g)</sub> ≥ 20 μs	0.7	2	
		$V_{\text{supply}} = +12V^{\dagger}$	R <sub>L</sub> = 10Ω,	t <sub>W(g)</sub> ≥ 20 μs	-0.8	- 2	V
VGTM .		$V_{\text{supply}} = -12V^{\dagger}$ ,	$R_L = 10 \Omega$ ,	t <sub>w(g)</sub> ≥ 20 μs	-0.8	-2	ľ
-		$V_{\text{supply}} = -12V^{\dagger}$ ,	$R_L = 10 \Omega$ ,	t <sub>w(g)</sub> ≥ 20 μs	0.9	2	
VTM	Peak On-State Voltage	I <sub>TM</sub> = ±12A,	IG = 50 mA,	See Note 6	± 1.6	± 2.1	~
	H-I-II O	V <sub>supply</sub> = +12V <sup>†</sup> , Initiating I <sub>TM</sub> = 100 mA	I <sub>G</sub> = 0,		5	30	m
IH Holding Current	$V_{\text{supply}} = -12V^{\dagger}$ , Initiating $I_{TM} = -100 \text{ m}$	IG = 0,		-9	- 30		
	Latching Current	$V_{\text{supply}} = +12V^{\dagger}$ ,	See Note 7			50	m
IL		$V_{\text{supply}} = -12V^{\dagger}$ ,	See Note 7		_		
dv/dt	Critical Rate of Rise of Off-State Voltage	V <sub>DRM</sub> = Rated V <sub>DRM</sub> ,	1 <sub>G</sub> = 0,	T <sub>C</sub> = 110°C	100		V/ <sub>l</sub>
dv/dt(c)	Critical Rise of Commutation Voltage	V <sub>DRM</sub> = Rated V <sub>DRM</sub> , See Figure 9	I <sub>TRM</sub> = ±4.2A,	T <sub>C</sub> = 85°C	5		V/



All voltages are with respect to Main Terminal 1.

NOTES: 6. These parameters must be measured using pulse techniques, t<sub>W</sub> ≤ 1 ms, duty cycle ≤ 2 %. Voltage-sensing contacts, separate from the current-carrying contacts, are located within 3,2 mm (1/8 inch) from the device body.

7. The triacs are triggered by a 15-V (open-circuit amplitude) pulse supplied by a generator with the following characteristics:

R<sub>G</sub> = 100 Ω, t<sub>W</sub> = 20 μs, t<sub>f</sub> ≤15 ns, t<sub>f</sub> ≤15 ns, t<sub>f</sub> ≤ 15 ns, t<sub>f</sub> ≤ 1 kHz.

## thermal characteristics

therma characteristics					_
PARAMETER	MIN	TYP	MAX	UNIT	
Rejc			1.8	•cw	
Bola	i		62.5	1	

**TIC Devices** 

62C 36727 D

TIC226A, TIC226B, TIC226C, TIC226D, TIC226E, TIC226M, TIC226S, TIC226N SILICON TRIACS

#### TYPICAL CHARACTERISTICS

GATE TRIGGER CURRENT

vs CASE TEMPERATURE

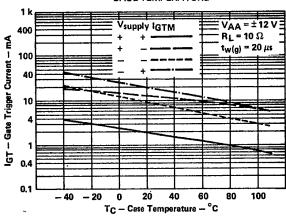
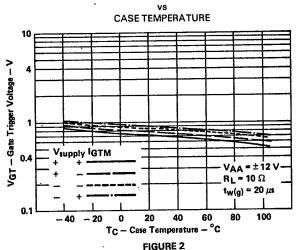


FIGURE 1

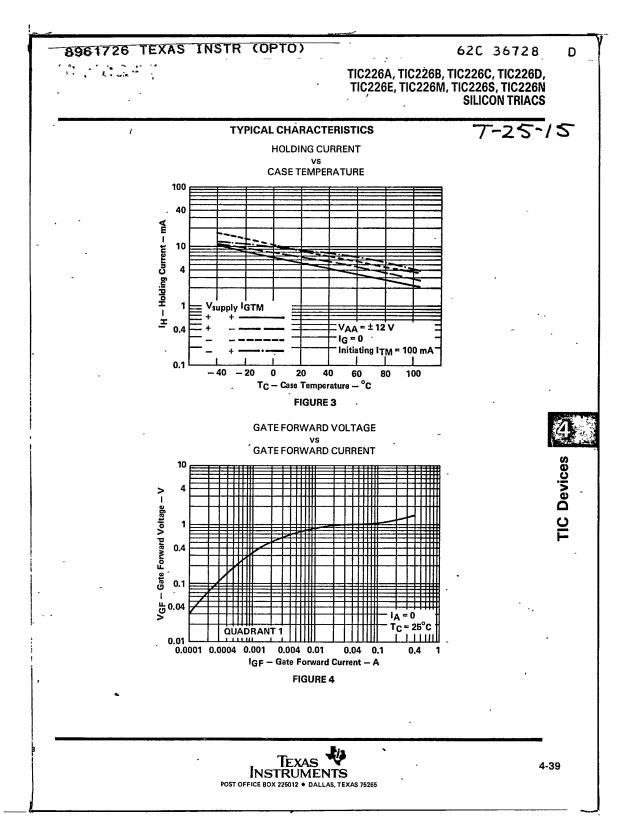
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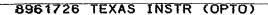
**TIC Devices** 

GATE TRIGGER VOLTAGE









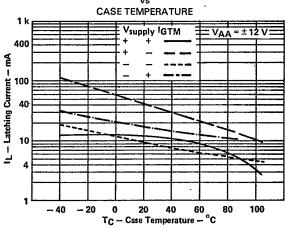
62C 36729

TIC226A, TIC226B, TIC226C, TIC226D, TIC226E, TIC226M, TIC226S, TIC226N **SILICON TRIACS** 

7-25-15

#### TYPICAL CHARACTERISTICS

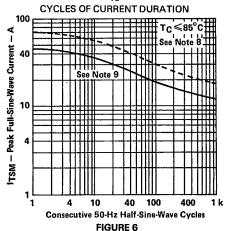
LATCHING CURRENT



TIC Devices

# FIGURE 5 THERMAL INFORMATION

SURGE ON-STATE CURRENT



- NOTES: 8. The dashed curve shows the maximum number of cycles of surge current recommended for safe operation provided the device is initially operating at, or below, the rated value of on-state current; however, during the surge period gate control of the device is initially at nonoperating thermal equilibrium.
  - The solid curve shows the maximum number of cycles of surge current for which gate control is guaranteed provided the device is initially at nonoperating thermal equilibrium.



62C 36730

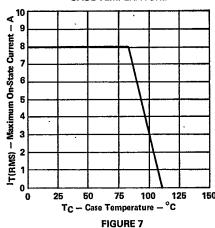
TIC226A, TIC226B, TIC226C, TIC226D, TIC226E, TIC226M, TIC226S, TIC226N **SILICON TRIACS** 

### THERMAL INFORMATION

T-25-15

MAXIMUM RMS ON-STATE CURRENT

CASE TEMPERATURE



MAXIMUM AVERAGE POWER DISSIPATED

RMS ON-STATE CURRENT

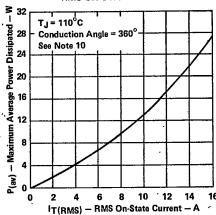


FIGURE 8

NOTE 10: For operation at current greater than 8 amps rms, see Figure 6.

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